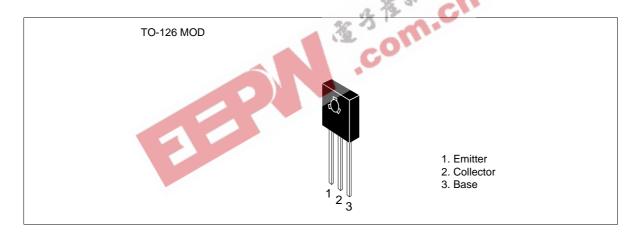
# Silicon PNP Epitaxial

# **HITACHI**

#### **Application**

Low frequency power amplifier complementary pair with 2SC1212 and 2SC1212A

#### **Outline**



#### **Absolute Maximum Ratings** ( $Ta = 25^{\circ}C$ )

		Ratings			
Item	Symbol	2SA743	2SA743A	Unit	
Collector to base voltage	V <sub>CBO</sub>	-50	-80	V	
Collector to emitter voltage	V <sub>CEO</sub>	-50	-80	V	
Emitter to base voltage	$V_{EBO}$	-4	-4	V	
Collector current	I <sub>c</sub>	<b>-1</b>	<b>–</b> 1	Α	
Collector power dissipation	P <sub>c</sub>	0.75	0.75	W	
	P <sub>c</sub> *1	8	8		
Junction temperature	Tj	150	150	°C	
Storage temperature	Tstg	-55 to +150	-55 to +150	°C	

Note: 1. Value at  $T_c = 25^{\circ}C$ .

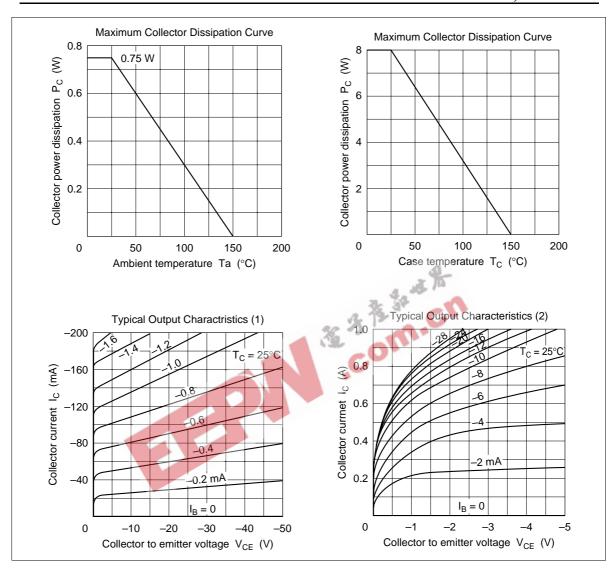


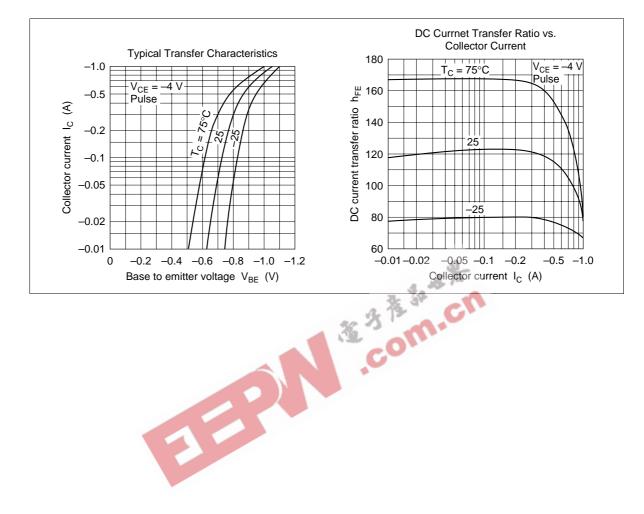
### **Electrical Characteristics** ( $Ta = 25^{\circ}C$ )

		2SA7	43		2SA	2SA743A			
Item	Symbol	Min	Тур	Max	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	-50	_	_	-80	_	_	V	$I_{\rm C} = -1 \text{ mA}, I_{\rm E} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	-50	_	_	-80	_	_	V	$I_{\rm C} = -10$ mA, $R_{\rm BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	-4	_	_	-4	_	_	V	$I_{E} = -1 \text{ mA}, I_{C} = 0$
Collector cutoff current	I <sub>CER</sub>	_	_	-20	_	_	_	μΑ	$V_{CE} = -50 \text{ V}, R_{BE} = 1$ $k\Omega$
	I <sub>CER</sub>	_	_	_	_	_	-20	a	$V_{CE} = -80 \text{ V}, R_{BE} = 1$ $k\Omega$
DC current tarnsfer ratio	h <sub>FE</sub> *1	60	120	200	60	120	200	15-	$V_{CE} = -4 \text{ V}, I_{C} = -50 \text{ mA}$
	h <sub>FE</sub>	20	-	_	20	3-7	7.		$V_{CE} = -4 \text{ V}, I_{C} = -1 \text{ A}$ (pulse)
Base to emitter voltage	$V_{BE}$	_	-0.65	-1.0	_	-0.65	1.0	V	$V_{CE} = -4 \text{ V}, I_{C} = -50 \text{ mA}$
Collector to emitter saturation voltage	V <sub>CE(sat)</sub>		-0.75	-1.5	_	-0.75	-1.5	V	$I_{\rm C} = -1 \text{ A}, I_{\rm B} = -0.1 \text{ A}$
Gain bandwidth product	f <sub>T</sub>		120	_	_	120	_	MHz	$V_{CE} = -4 \text{ V}, I_{C} = -30 \text{ mA}$

Note: 1. The 2SA743 and 2SA743A is grouped by  $h_{\text{FE}}$  as follows.

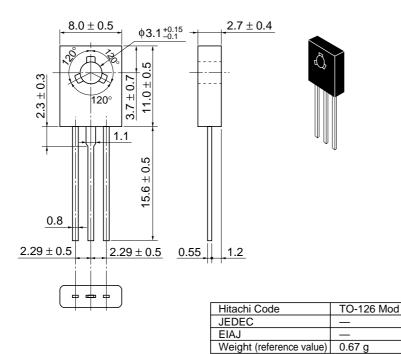
В	С
60 to 120	100 to 200







Unit: mm



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Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109 URI

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#### For further information write to:

Hitachi Semiconductor (America) Inc. 179 East Tasman Drive, San Jose,CA 95134 Tel: <1> (408) 433-1990 Fax: <1>(408) 433-0223 Hitachi Europe GmbH Electronic components Group Dornacher Stra§e 3 D-85622 Feldkirchen, Munich Germany Tel: <49> (89) 9 9180-0

Fax: <49> (89) 9 29 30 00 Hitachi Europe Ltd. Electronic Components Group.

Whitebrook Park

Lower Cookham Road

Maidenhead Berkshire SL6 8YA, United Kingdom Tel: <44> (1628) 585000 Fax: <44> (1628) 778322

Hitachi Asia Pte. Ltd. 16 Collyer Quay #20-00 Hitachi Tower Singapore 049318 Tel: 535-2100 Fax: 535-1533

Hitachi Asia Ltd

Taipei Branch Office 3F, Hung Kuo Building. No.167 Tun-Hwa North Road, Taipei (105) Tel: <886> (2) 2718-3666 Fax: <886> (2) 2718-8180

Hitachi Asia (Hong Kong) Ltd. Group III (Electronic Components) 7/F., North Tower, World Finance Centre, Harbour City, Canton Road, Tsim Sha Tsui, Kowloon, Hong Kong Tel: <852> (2) 735 9218 Fax: <852> (2) 730 0281 Telex: 40815 HITEC HX

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